

Amendments to the Claims

The listing of claims will replace all prior versions, and listings of claims in the application.

1. (currently amended) A cleaning device for process gases that is configured to generate ~~generates~~ clean process gas from contaminated process gas in a reflow soldering system, comprising:

a ~~plurality of cleaning chamber chambers comprising containing,~~

a cleaning liquid configured to clean the contaminated process gas for
~~said process gas, each of said cleaning chamber allowing chambers allowing~~ the
contaminated process gas to flow therein via a supply line and allowing the cleaned
process gas to flow therefrom via a discharge line[.,,]; and

a deposition wall having a surface, the surface being configured to receive
a film of the cleaning liquid and being configured to be an outer wall of the cleaning
device

~~wherein the cleaning chambers are each formed by a plurality of modules~~
~~in parallel to allow for a predetermined throughput and in successive order to~~
~~allow for a predetermined degree of purity for the process gas.~~

2. (currently amended) The cleaning device according to claim [[1]] 10, wherein
the plurality of modules include modules having different operative principles of
deposition that are connected one after the other in series.

3. (previously presented) The device according to claim 2, wherein a flow path
for the cleaning liquid extends through the series-connected modules in such a manner
that the direction of flow of the cleaning liquid is opposite to the direction of flow of the
process gas.

4. (currently amended) The cleaning device according to claim [[1]] 10, wherein the cleaning liquids have different cleaning properties, such that respective ones of which are provided in respective ones of ~~the~~ a plurality of the cleaning chambers corresponding to each of the modules ~~Modules~~ arranged in the successive order.

5. (currently amended) The cleaning device according to claim 1, wherein ~~at least a part of each of the plurality of cleaning chamber comprises chambers contains a corresponding bath including~~ comprising the cleaning liquid, the supply line coupled below the liquid level of the bath.

6. (canceled)

7. (currently amended) The cleaning device according to claim [[6]] 1, wherein ~~there are a plurality of the deposition walls that~~ are arranged perpendicular or with a slope with respect to each other in ~~the plurality of the cleaning chamber chambers~~ and the supply ~~means~~ for the cleaning liquid ~~are~~ is arranged in an area on top of edges of the plurality of deposition walls.

8. (currently amended) The cleaning device according to claim 1, wherein at least one respective injection opening for the cleaning liquid is directed into ~~at least part of each of the plurality of cleaning chamber chambers~~.

9. (currently amended) The cleaning device according to claim 1, wherein ~~at least part of each of the plurality of cleaning chamber chambers~~ comprises a respective outlet that is connected to a clarifying device for the cleaning liquid.

10. (new) The cleaning device according to claim 1, wherein the cleaning chamber comprises a plurality of modules arranged in parallel configured to allow for a predetermined throughput and, in successive order, to allow for a predetermined degree of purity for the process gas.